

IRF7306QTRPBF-VB Datasheet Dual P-Channel 30-V (D-S) MOSFET

G1 0

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^{d, e}	Q _g (Typ.)		
- 30	0.035 at V _{GS} = - 10 V	- 7.3	17 nC		
- 30	0.045 at V _{GS} = - 4.5 V	- 6.3	17110		

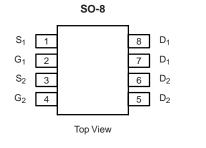
FEATURES

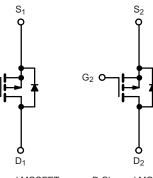
- Halogen-free
- Trench Power MOSFET
- 100 % UIS Tested

APPLICATIONS

Load Switches







P-Channel MOSFET

P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_{A}	= 25 °C, unless othe	erwise noted			
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 30	V	
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		- 7.3 ^e		
Continuous Drain Current ($T_1 = 150 \ ^{\circ}C$)	T _C = 70 °C		- 7.0 ^e		
$Continuous Drain Current (T_j = 150 C)$	T _A = 25 °C	I _D	- 7.3 ^{a, b}		
	T _A = 70 °C		- 5.9 ^{a, b}	•	
Pulsed Drain Current	I _{DM}	- 32 ^e	— A		
	T _C = 25 °C	1	- 4.1		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.0 ^{a, b}		
Avalanche Current		I _{AS}	- 20		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	20	mJ	
	T _C = 25 °C		5.0		
Maximum Davies Disain atian	T _C = 70 °C		3.2	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	vv	
	T _A = 70 °C	1	1.6 ^{a, b}		
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W		
Maximum Junction-to-Foot	Steady State	R _{thJF}	20	25	0/11		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 85 °C/W.

d. Based on T_C = 25 °C.

e. Limited by package.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	<u> </u>				1	1
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1 250 4		- 31		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		4.5		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 3.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 55 \text{ °C}$			- 1 - 5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge$ - 10 V, V_{GS} = - 10 V	- 30			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -10 \text{ V}, \text{ I}_{D} = -6.3 \text{ A}$ $V_{GS} = -4.5 \text{ V}, \text{ I}_{D} = -6.2 \text{ A}$		0.035		Ω
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 6.1 A		23		S
Dynamic ^b					1	
Input Capacitance	C _{iss}			1350		
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		215		pF
Reverse Transfer Capacitance	C _{rss}			185		
Total Gate Charge	Qg	$V_{DS} = -15 \text{ V}, \text{ V}_{GS} = -10 \text{ V}, \text{ I}_{D} = -6.1 \text{ A}$		32 15	50 25	
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 6.1 A		4		nC
Gate-Drain Charge	Q _{gd}			7.5		
Gate Resistance	R _g	f = 1 MHz		5.8		Ω
Turn-On Delay Time	t _{d(on)}			10	15	
Rise Time	t _r	V_{DD} = - 15 V, R_L = 15 Ω		8	15	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 10 V, R_g = 1 Ω		45	70	
Fall Time	t _f			12	25	
Turn-On Delay Time	t _{d(on)}			42	70	ns
Rise Time	t _r	V_{DD} = - 15 V, R _L = 15 Ω		35	60	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 1 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		40	70	
Fall Time	t _f			16	30	
Drain-Source Body Diode Characterist	ics	· · · ·			•	
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 4.1	٨
Pulse Diode Forward Current	I _{SM}				- 32	A
Body Diode Voltage	V _{SD}	I _S = - 2 A, V _{GS} = 0 V		- 0.75	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}			34	60	ns
Body Diode Reverse Recovery Charge	Q _{rr}			22	40	nC
Reverse Recovery Fall Time	t _a	I _F = - 2 A, dl/dt = 100 A/μs, T _J = 25 °C		11		
Reverse Recovery Rise Time				23		ns

Notes:

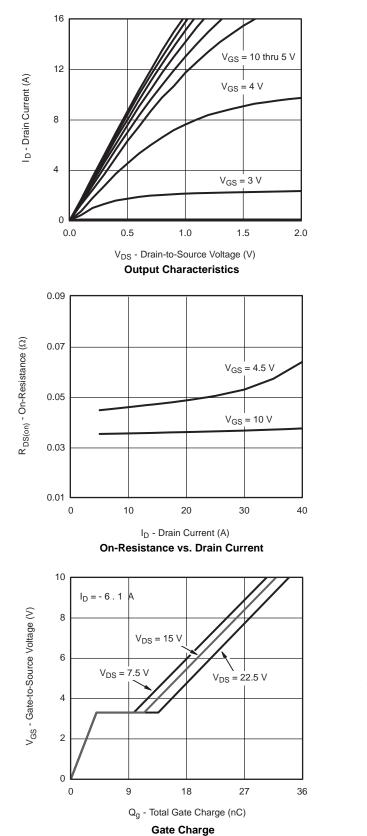
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

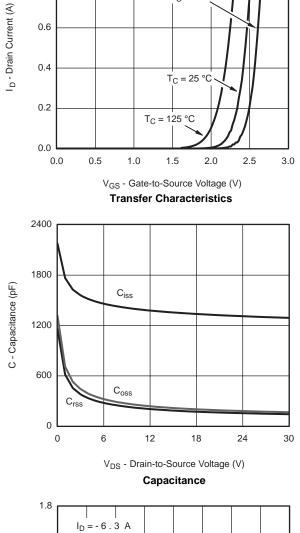
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



 $T_C = -55^{\circ}C$

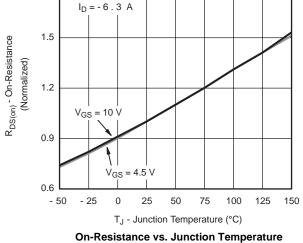


TYPICAL CHARACTERISTICS 25 C, unless otherwise noted

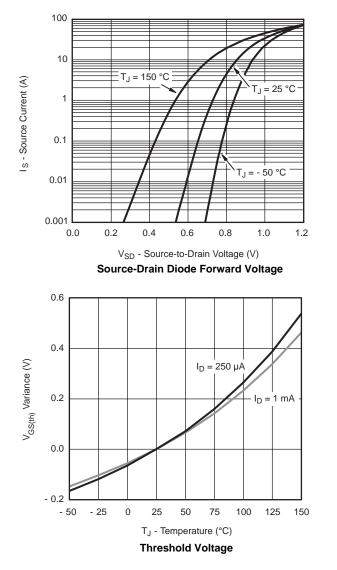


1.0

0.8

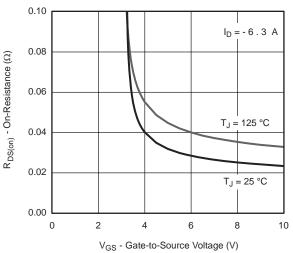




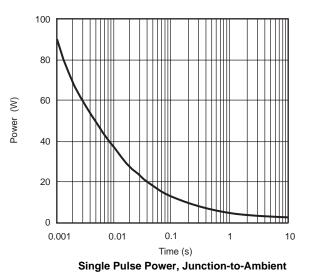


I_D - Drain Current (A)

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



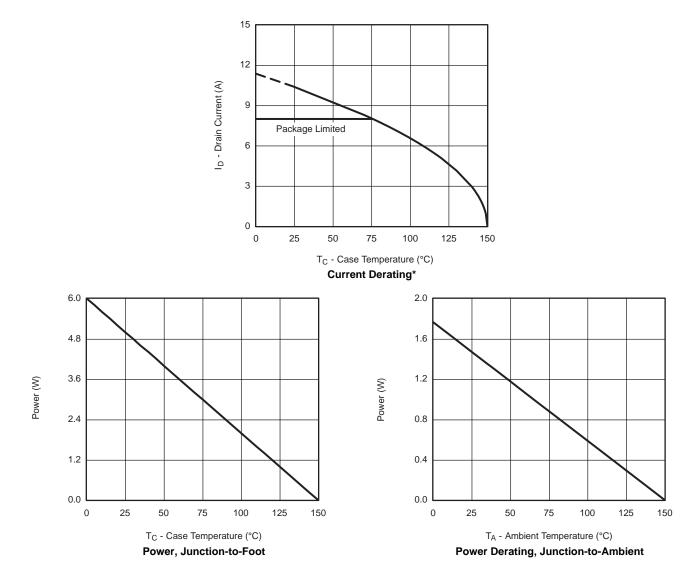
On-Resistance vs. Gate-to-Source Voltage



100 Limited by R_{DS(on)} 10 100 µs 1 ms 10 ms 100 ms 0.1 10 s T_A = 25 °C Single Pulse 1 s. DC **BVDSS** Limited 0.01 0.1 10 100 1 V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified Safe Operating Area



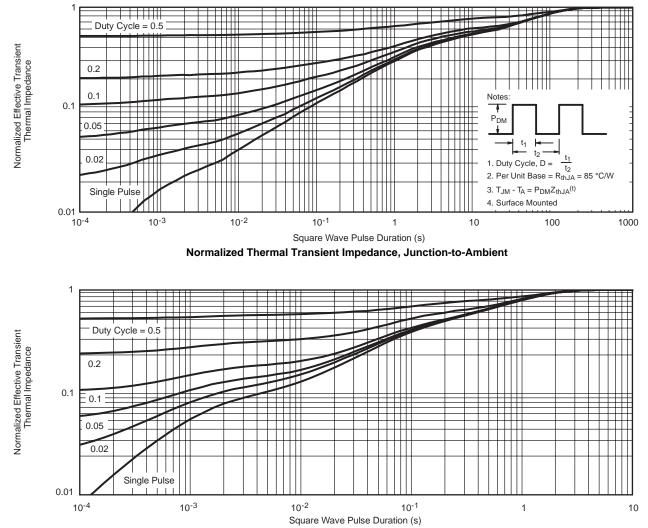
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



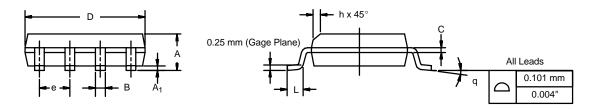
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012

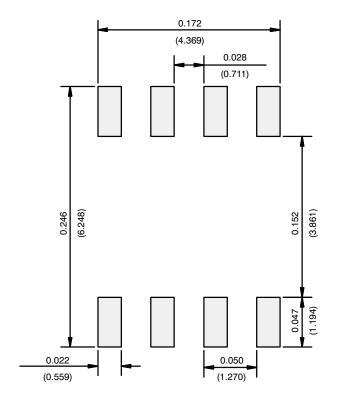




	MILLIMETERS		INCHES		
DIM	Min	Мах	Min	Max	
A	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
E	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498					



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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